

**IN THE CLAIMS:**

Please cancel claim 2 without prejudice.

Please amend the claim as follows:

1. (Amended) A power semiconductor package, comprising:  
a bottom leadframe having a bottom plate portion and at least one first terminal  
extending from the bottom plate portion;  
at least one second terminal being co-planar with the first terminal;  
a third terminal;  
a semiconductor power MOSFET die having a bottom surface defining a drain  
connection and a top surface on which a first metalized region defining a source and a second  
metalized region defining a gate are disposed, the bottom surface being coupled to the bottom  
plate of the leadframe such that the first terminal is electrically connected to the drain;  
a copper plate coupled to and spanning a substantial part of the first metalized  
region defining the source connection; [and]  
at least one beam portion being sized and shaped to couple the copper plate  
portion to the at least one second terminal such that it is electrically coupled to the source; and  
a wire bond coupling the gate to a third terminal.

**REMARKS**

Applicants respectfully request reconsideration and allowance of claims 1, and 3-29 which are pending in the above-identified application. Claims 1-26 are rejected or objected to and claims 27-29 are allowed. Applicants have amended claim 1 and canceled claim 2.

At page 2 of the Office Action, the Examiner rejected claims 1, 3-7, and 10-13 under 35 U.S.C. §103 as being unpatentable over the Kalfus reference. In response, Applicant has amended claim 1 to include the limitation of claim 2 (a claim that the Examiner has deemed allowable). Accordingly, Applicants submit that claim 1 is allowable over the cited art of record. Further, claims 3-7, and 10-13 depend from claim 1 and contain all of the limitations thereof as well as other limitations which are neither disclosed nor suggested by the prior art of record.